

**IN THE CLAIMS:**

**Please enter the following amendments and/or additions:**

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1. (*Previously Amended*) A packaged integrated circuit, comprising at least one radio frequency component included in an integrated circuit die directly connected by wire to a radio frequency antenna, said integrated circuit die being included in said packaged integrated circuit, wherein said radio frequency antenna comprises a portion of the package of said packaged integrated circuit and is excluded from said integrated circuit die.

Q1 2. (*Previously Amended*) The packaged integrated circuit according to claim 1, wherein said packaged integrated circuit comprises an integrated circuit package which houses said at least one radio frequency component and wherein said radio frequency antenna comprises at least one metal object that is a portion of the package of said packaged integrated circuit.

3. (*Cancelled*)

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4. (*Previously Amended*) The packaged integrated circuit according to claim 2, wherein said radio frequency antenna is disposed on a metal frame of said integrated circuit package.

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5. (*Previously Amended*) The packaged integrated circuit according to claim 1, wherein said radio frequency antenna comprises at least one planar metal pattern separated from a grounded metal plane by an insulating layer.

6. *(Previously Amended)* The packaged integrated circuit according to claim 5, wherein said planar metal pattern is a metal slot-pattern and said insulating layer is a ceramic layer.

7. *(Previously Amended)* The packaged integrated circuit according to claim 6, wherein said slot pattern comprises a first S-shaped slot.

8. *(Previously Amended)* The packaged integrated circuit according to claim 7, wherein said radio frequency antenna comprises a second S-shaped slot rotated 90 degrees with regard to said first S-shaped slot.

9. *(Previously Amended)* The packaged integrated circuit according to claim 1, wherein said integrated circuit package is a Ball Grid Array package.

10. *(Previously Amended)* The packaged integrated circuit according to claim 1, wherein said integrated circuit package is a Quad Flat Pack package.

11. *(Previously Amended)* The packaged integrated circuit according to claim 1, wherein said integrated circuit package is a Small Outline package.

12. *(Previously Amended)* A radio frequency module comprising at least one packaged integrated circuit according to claim 1.

13. (*Currently Amended*) A packaged module, comprising:  
an integrated circuit die having at least one radio frequency component;  
a radio frequency antenna;  
a shield interposed between said integrated circuit die and said radio frequency antenna,  
wherein said integrated circuit is directly connected to said radio frequency antenna by metal wiring  
routed through said shield, and  
wherein said radio frequency antenna comprises a portion of the package of said packaged  
module and is excluded from said integrated circuit die.

14. (*Previously Added*) The module according to claim 13, wherein said radio frequency  
antenna is comprised of metal.

15. (*Previously Added*) The module according to claim 13, wherein said radio frequency  
antenna comprises at least one planar metal pattern separated from a grounded metal plane by an  
insulating layer.

16. (*Previously Added*) The module according to claim 15, wherein said planar metal pattern  
is a metal slot-pattern and said insulating layer is ceramic layer.

17. (*Previously Added*) The module according to claim 16, wherein said slot pattern is a first  
S-shaped slot.

18. (*Previously Added*) The module according to claim 17, wherein said radio frequency antenna comprises a second S-shaped slot rotated 90 degrees with respect to said first S-shaped slot.

19. (*Previously Added*) The module according to claim 13, wherein said radio frequency antenna comprises a plurality of via holes arranged around the periphery of said antenna.

20. (*Previously Amended*) The module according to claim 19, wherein two of said plurality of via holes are disposed opposite each other on said periphery of said antenna.

21. (*Previously Amended*) The module according to claim 13, further comprising an integrated circuit package having a metal frame, said integrated circuit package encapsulating said shield and said integrated circuit die.

22. (*Previously Amended*) The module according to 21, wherein said radio frequency antenna is disposed on said metal frame of said integrated circuit package.

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22. (*Previously Added*) The module according to 21, wherein said radio frequency antenna is disposed on said metal lead frame of said integrated circuit package.

23. (*Previously Added*) The module according to claim 13, wherein said integrated circuit package is a Ball Grid Array package.

24. (*Previously Added*) The module according to claim 13, wherein said integrated circuit package is a Quad Flat Pack package.

104 25. (*Previously Added*) The module according to claim 13, wherein said integrated circuit package is a Small Outline package.

26. (*Previously Added*) The module according to claim 13, wherein said shield is connected to an electrical ground.

27. (*Previously Added*) The packaged integrated circuit according to claim 1, wherein the length of said wire is  $\frac{1}{4}\lambda$  to  $\frac{1}{2}\lambda$ , wherein  $\lambda$  represents the wavelength of a transmitted or received radio signal.

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